

Please amend the last paragraph of page 4 of the specification as follows.

B1
The invention further comprises articles of manufacture comprising substrates such as a microelectronic device substrate, particularly a semiconductor chip substrate, having plated thereon composition of the invention, including first and second circuit traces separated by a barrier layer, obtainable by methods of the invention. The invention still further comprises articles of manufacture comprising substrates such as a microelectronic device such as semiconductor chips or semiconductor packaging having plated thereon solderable finish compositions of the invention.